

REMARKS

This application has been reviewed in light of the Office Action dated April 2, 2008.

Claims 1-11 and 13-36 are presented for examination. Claims 13-33 have been allowed. Claim 12 has been cancelled without prejudice. Claims 1 and 2 have been amended. Claims 34-36 have been added. Claims 1, 13, 23 and 34-36 are independent. Favorable review is respectfully requested.

Claim 1 has been amended to incorporate the features of claim 12; claim 12 has accordingly been cancelled. Claim 2, dependent from claim 1, has been amended to recite a semiconductor device, consistent with the language of claim 1. New claims 34 and 35 recite the subject matter of claims 6 and 7, respectively, in independent form. New claim 36 includes the features of the previous claim 1, and further recites that each lead (16) has a second surface substantially coplanar with a surface of the interposer, the first surface (38) displaced from and substantially parallel to the second surface. Support for this claim feature is found in the specification at least at page 6, line 30, to page 7, line 3, and FIGS. 3 and 4. No new matter has been added.

The applicants wish to express their appreciation to the Examiner for the allowance of claims 13-33. The applicants also note with appreciation the Examiner's comment that claims 6-10 and 12 would be allowable if rewritten in independent form. In response to the Examiner's comments, claims 6 and 7 have been rewritten in independent form and presented as new claims 34 and 35, respectively. Independent claim 1 has been amended to incorporate the features of claim 12. Independent claims 1, 34 and 35, together with dependent claims 2-11, are thus now in condition for allowance.

Claim 2 was objected to because of informalities; the Examiner pointed out that claim 2 recited "semiconductor die" rather than "semiconductor device." Claim 2 has been revised in accordance with the Examiner's comments.

Claims 1-5 and 11 were rejected under 35 U.S.C. § 102(e) as anticipated by Sakamoto et al. (U.S. Patent Application Pub. No. 2005/0056916). Independent claim 1 has been amended to include the features of claim 12; accordingly, the rejection is believed to have been overcome.

Furthermore, the applicants respectfully submit that new independent claim 36 is patentably distinct from the cited art, for the following reasons.

Claim 36, directed to a semiconductor device package, recites all of the features of claim 1 (before the amendment to claim 1 presented herein), including a lead frame including a plurality of leads and a plurality of first interposers. Each of the leads (16) includes a first surface (38) exposed from the package body (30). Claim 36 additionally recites that each lead (16) has a second surface substantially coplanar with a surface of the interposer, the first surface (38) displaced from and substantially parallel to the second surface. In the embodiment taught in the specification and shown in FIG. 3, lead (16) does not have a uniformly planar underside surface, but rather has a first surface (38) displaced from a second surface. In FIG. 3, the first surface is indicated by numeral 38, while the second surface is indicated by diagonal hatching. The second surface is coplanar with the underside of interposer 20, as shown in FIG. 3.

Sakamoto et al. is understood to disclose a device in which a conductive path 51 (characterized by the Examiner as a lead frame 51A-51C) has a surface exposed from package body 50 (Sakamoto et al., FIGS. 1A and 8). This surface is shown as the underside of conductor 51A, 51B and 51C in Sakamoto et al. The applicants wish to point out that conductors 51A, 51B, 51C are uniformly coplanar on their underside. Assuming arguendo that portion 51B may be viewed as a lead and portion 51C as an interposer, the underside surfaces of the lead and the interposer are entirely coplanar. In the device of claim 36, by contrast, the lead has a first surface that is displaced from the second surface, while the second surface is substantially coplanar with a surface of the interposer. It is submitted that Sakamoto et al. neither discloses nor suggests this feature of claim 36. Accordingly, claim 36 is not anticipated by the reference.

In view of the foregoing amendments and remarks, favorable consideration and early passage to issue of the application are respectfully requested.

No fees are believed to be due. The Commissioner is nevertheless authorized to charge any required fees to Deposit Account No. 23-1665.

The applicants' undersigned attorney may be reached by telephone at 212-551-2625. All correspondence should continue to be directed to the address given below, which is the address associated with Customer Number 27267.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Jay H. Anderson", with a long horizontal flourish extending to the right.

Jay H. Anderson
Registration Number 38,371
Attorney for Applicants
Tel: (212) 551-2625
Fax: (212) 490-0536

WIGGIN AND DANA LLP
One Century Tower, P.O. Box 1832
New Haven, CT 06508

Date: July 2, 2008

\\16832\\4\\719944.1